TOSHIBA BIPOLAR DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

TD62001P, TD62001AP, TD62001F, TD62001AF, TD62002P TD62002AP, TD62002F, TD62002AF, TD62003P, TD62003AP, TD62003F TD62003AF, TD62004P, TD62004AP, TD62004F, TD62004AF

7CH DARLINGTON SINK DRIVER

The TD62001P / AP / F / AF Series are high–voltage, high–current darlington drivers comprised of seven NPN darlington pairs. All units feature integral clamp diodes for switching inductive loads.

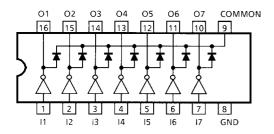
Applications include relay, hammer, lamp and display (LED) drivers.

FEATURES

- Output current (single output) 500 mA MAX.
- High sustaining voltage output 35 V MIN. (TD62001P / F Series) 50 V MIN. (TD62001AP / AF Series)
- Output clamp diodes
- Inputs compatible with various types of logic
- Package Type-P, AP: DIP-16 pin
- Package Type-F, AF: SOP-16 pin

TYPE	INPUT BASE RESISTOR	DESIGNATION
TD62001P / AP / F / AF	External	General Purpose
TD62002P / AP / F / AF	10.5-kΩ + 7 V Zenner diode	14~25 V PMOS
TD62003P / AP / F / AF	2.7 kΩ	TTL, 5 V CMOS
TD62004P / AP / F / AF	10.5 kΩ	6~15 V PMOS, CMOS

PIN CONNECTION (TOP VIEW)

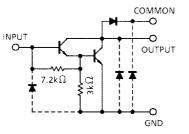


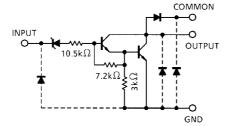
TD62001P / AP TD62002P / AP TD62003P / AP TD62004P / AP
DIP16-P-300-2.54A
TD62001F / AF TD62002F / AF TD62003F / AF TD62004F / AF
CHERTHERE
SOP16-P-225-1.27

Weight DIP16-P-300-2.54A : 1.11 g (Typ.) SOP16-P-225-1.27 : 0.16 g (Typ.)

SCHEMATICS (EACH DRIVER)

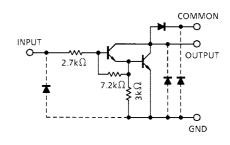
TD62001P / AP / F / AF



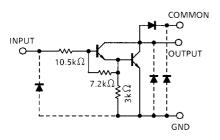


TD62002P / AP / F / AF

TD62003P / AP / F / AF



TD62004P / AP / F / AF



Note: The input and output parasitic diodes cannot be used as clamp diodes.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTI	SYMBOL	RATING	UNIT		
Output Sustaining	P, F		-0.5~35	V	
Voltage	AP, AF	V _{CE (SUS)}	-0.5~50	v	
Output Current		I _{OUT}	500	mA / ch	
Input Voltage		V _{IN} (Note 1)	-0.5~30	V	
Input Current		I _{IN} (Note 2)	25	mA	
Clamp Diode	P, F	V _R	35	V	
Reverse Voltage	AP, AF	٧R	50	v	
Clamp Diode Forward Current		١ _F	500	mA	
	Р		1.0		
Power Dissipation	AP	PD	1.47	W	
·	F, AF	5	0.54 / 0.625 (Note 3)		
Operating	Р	т	-30~75	°C	
Temperature	AP, F, AF	T _{opr}	-40~85	U	
Storage Temperature		T _{stg}	T _{stg} -55~150		

Note 1: Except TD62001P / AP / F / AF

Note 2: Only TD62001P / AP / F / AF

Note 3: On glass epoxy PCB (30 × 30 × 1.6 mm Cu 50%)

RECOMMENDED OPERATING CONDITIONS (Ta = -40~85°C and Ta = -30~75°C for only Type-P)

CHARACTERISTIC		SYMBOL	CONDITION		MIN	TYP.	MAX	UNIT	
Output Sustaining	P, F				0	—	35	v	
Voltage	AP, AF			0	_	50	v		
	AP	Ιουτ	T _{pw} = 25 ms 7 Circuits	Duty = 10%	0	_	370	mA / ch	
				Duty = 50%	0	_	130		
Output Current	Р			Duty = 10%	0	_	295		
Output Current	F		Ta = 85°C T _i = 120°C	Duty = 50%	0	_	95		
	F, AF		.]	Duty = 10%	0	_	233		
	Ι, ΑΙ			Duty = 50%	0	_	70		
Input Voltage	Except TD62001P / AP / F / AF	V _{IN}			0	_	24	V	
Input Voltage (Output On)	TD62002	V _{IN (ON)}	I _{OUT} = 400 mA h _{FE} = 800		14.5	_	24	v	
	TD62003				2.8	_	24		
(TD62004			6.2	_	24			
	TD62001	VIN (OFF)			0	_	0.6		
Input Voltage	TD62002				0	_	7.4	- V	
(Output Off)	TD62003				0	_	0.7		
	TD62004				0	_	1.0		
Input Current	Only TD62001	I _{IN}			0	_	10	mA	
Clamp Diode Reverse	P, F	\/_			_	_	35	v	
Voltage	AP, AF	V _R				_	50		
Clamp Diode Forward C	urrent	١ _F				_	350	mA	
	Р	AP P _D	Ta = 85°C			_	0.6		
Power Dissipation	AP		1a - 03 C			_	0.76	W	
	AF, F		Ta = 85°C	(Note)	_	_	0.325		

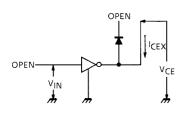
Note: On glass epoxy PCB (30 × 30 × 1.6 mm Cu 50%)

ELECTRICAL CHARACTERISTICS (Ta = 25°C unless otherwise noted)

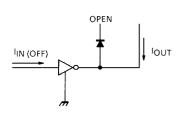
CHARACTERIS	CHARACTERISTIC SYMBOL CIR- CUIT TEST CONDITION		CONDITION	MIN	TYP.	MAX	UNIT		
			1	V _{CE} = 50 V, Ta = 25°C		_	_	50	
Output Leakage	AP, AF			V _{CE} = 50 V, Ta = 85°C			_	100	- μΑ
	F	lan.		V _{CE} = 35 V, Ta = 25°C		_	_	50	
Current	Г	ICEX		V _{CE} = 35 V, Ta = 85°C			_	100	
	Р			V _{CE} = 35 V, Ta = 25°C			_	50	
	Г			V _{CE} = 35 V, Ta = 75°C		_	_	100	
			2	I _{OUT} = 350 mA, I _{IN} = 500 μA		-	1.3	1.6	
Collector-Emitter Saturation	on Voltage	V _{CE (sat)}		I _{OUT} = 200 i	mA, I _{IN} = 350 μA	-	1.1	1.3	V
				I _{OUT} = 100 i	mA, I _{IN} = 250 μA	_	0.9	1.1	
DC Current Transfer Ratio		h _{FE}	2	V _{CE} = 2 V, I	_{OUT} = 350 mA	1000	-	_	
	TD62002			V _{IN} = 20 V,	I _{OUT} = 350 mA	_	1.1	1.7	
Input Current (Output On)	TD62003	I _{IN (ON)}	3	V _{IN} = 2.4 V, I _{OUT} = 350 mA			0.4	0.7	mΑ μΑ
· · · /	TD62004			V _{IN} = 9.5 V, I _{OUT} = 350 mA			0.8	1.2	
Input Current	Р		4	I _{OUT} = 500 μA, Ta = 75°C		50	65		
(Output Off)	AP, F, AF	I _{IN (OFF)}	4	I _{OUT} = 500 μA, Ta = 85°C		50	65	_	
	TD62002	V _{IN (ON)}	5	V _{CE} = 2 V	I _{OUT} = 350 mA		_	13.7	V
	1002002				I _{OUT} = 200 mA	-	—	11.4	
Input Voltage	TD62003				I _{OUT} = 350 mA	_	-	2.6	
(Output On)	1002003			$h_{FE} = 800$	I _{OUT} = 200 mA	_	-	2.0	
	TD62004				I _{OUT} = 350 mA		_	4.7	
	1002004				I _{OUT} = 200 mA		_	4.4	
	AP, AF			V _R = 50 V, Ta = 25°C			_	50	
	AI , AI			V _R = 50 V, Ta = 85°C			-	100	-μΑ
Clamp Diode	F	la	6	V _R = 35 V, Ta = 25°C			_	50	
Reverse Current	1	F I _R	0	V _R = 35 V, Ta = 85°C			_	100	
	D			V _R = 35 V, Ta = 25°C			-	50	
	I			V _R = 35 V, Ta = 75°C		_	-	100	
Clamp Diode Forward Volt	age	VF	7	I _F = 350 mA		_	-	2.0	V
Input Capacitance		C _{IN}	—				15	_	pF
Turn-On Delay	P, F	t _{ON}	8	V_{OUT} = 35 V, R _L = 87.5 Ω C _L = 15 pF		_	0.1		
	AP, AF	NUV		V_{OUT} = 50 V, R _L = 125 Ω C _L = 15 pF		_	0.1		- µs
Turn-Off Delay	P, F	torr	8	V_{OUT} = 35 V, R _L = 87.5 Ω C _L = 15 pF		_	0.2	_	
Turri On Delay	AP, AF	toff	0	V _{OUT} = 50 \ C _L = 15 pF	/, R _L = 125 Ω	-	0.2	_	

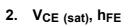
TEST CIRCUIT

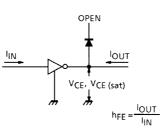
1. ICEX



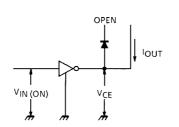
4. I_{IN (OFF)}



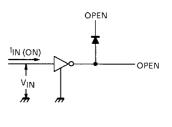




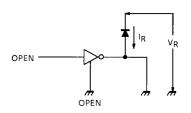
5. V_{IN (ON)}



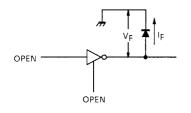
3. IIN (ON)



6. I_R

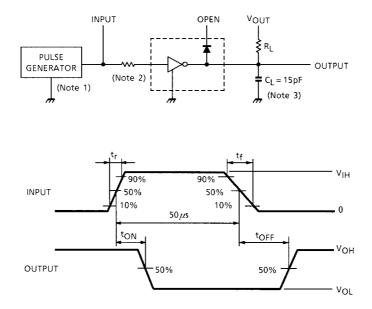


7. V_F



8. t_{ON}, t_{OFF}

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Note 1: Pulse width 50 μ s, duty cycle 10% Output impedance 50 Ω , t_r ≤ 5 ns, t_f ≤ 10 ns

Note 2: See below

INPUT CONDITION

TYPE NUMBER	R1	VIH
TD62001P / AP / F / AF	2.7 kΩ	3 V
TD62002P / AP / F / AF	0	13 V
TD62003P / AP / F / AF	0	3 V
TD62004P / AP / F / AF	0	8 V

Note 3: C_L includes probe and jig capacitance.

PRECAUTIONS for USING

This IC does not include built-in protection circuits for excess current or overvoltage.

If this IC is subjected to excess current or overvoltage, it may be destroyed.

Hence, the utmost care must be taken when systems which incorporate this IC are designed.

Utmost care is necessary in the design of the output line, COMMON and GND line since IC may be destroyed due to short–circuit between outputs, air contamination fault, or fault by improper grounding.

500

400

300

200

100

0

0

TD6200XF/A Ta = 25°C

ACTIVE

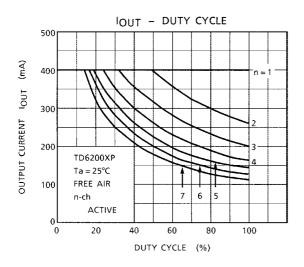
20

40

On PCB

n-ch

OUTPUT CURRENT JOUT (mA)



IOUT - DUTY CYCLE

n = 1

4

100

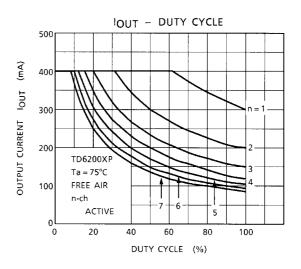
6

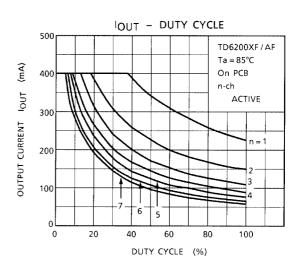
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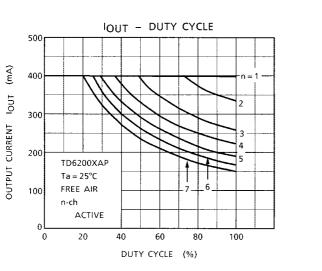
DUTY CYCLE (%)

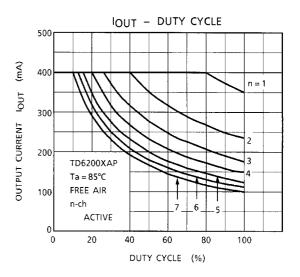
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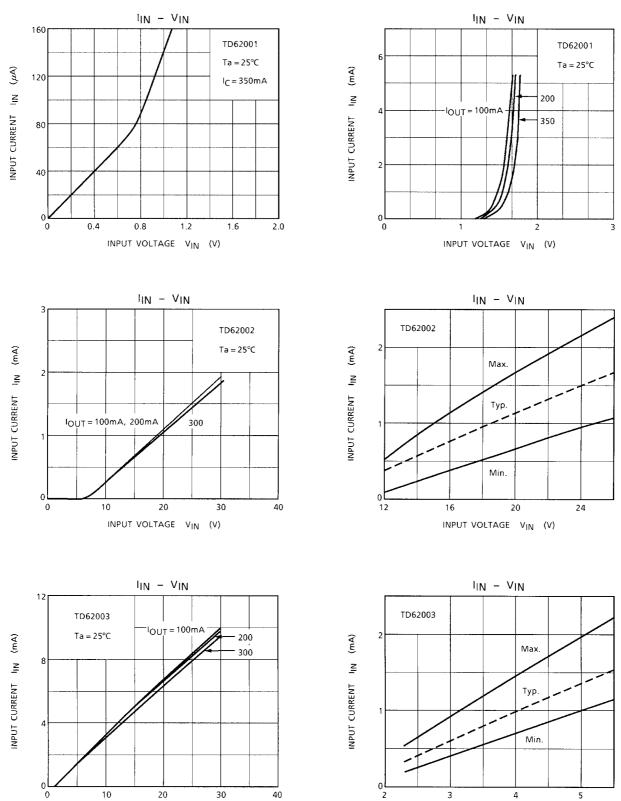
80





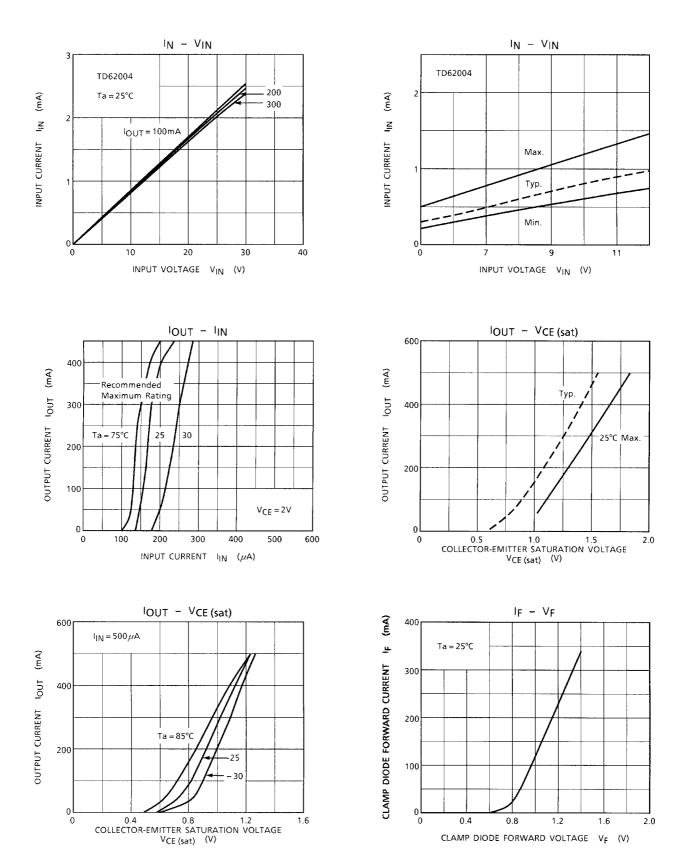


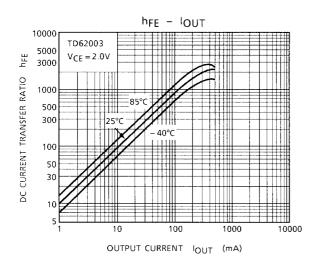


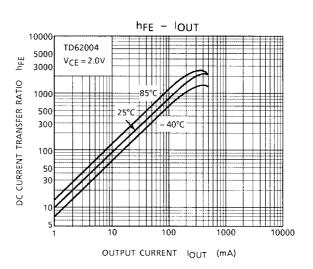


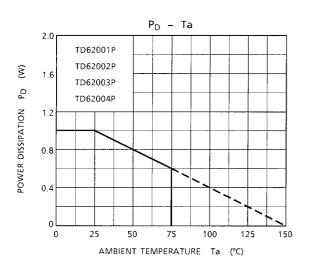
INPUT VOLTAGE V_{IN} (V)

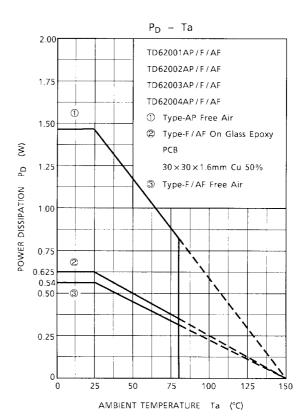
INPUT VOLTAGE VIN (V)







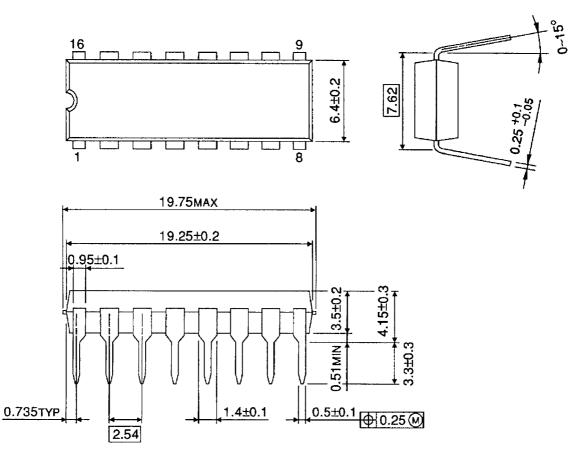




PACKAGE DIMENSIONS

DIP16-P-300-2.54A

Unit : mm



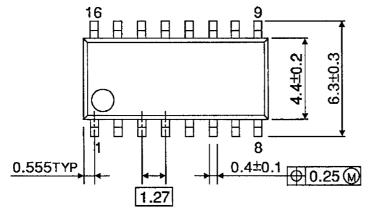
Weight: 1.11 g (Typ.)

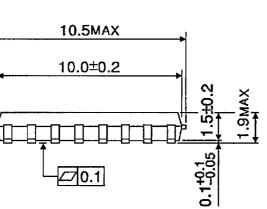
[5.715] (225mil)

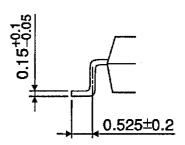
PACKAGE DIMENSIONS

SOP16-P-225-1.27

Unit : mm







Weight: 0.16 g (Typ.)

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